

09/14/06

09-18-2006



To the Director of the U.S. Patent ar.

103308407

Documents or the new address(es) below.

1. Name of conveying party(ies)Yoshiro Aoki, Riyuusuke Kasamatsu,
Hideki Nishihata, Seiichi NakamuraAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) June 23, 2006

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: Sumco Corporation

Internal Address:

Street Address: 2-1, Shibaura 1-chome

City: Minato-ku

State: Tokyo

Country: Japan

Zip:

Additional name(s) & address(es) attached? ☐ Yes ☒ No**4. Application or patent number(s):**

A. Patent Application No.(s)

11/471,750

☐ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Anton E. Skaugset

Internal Address: Kolisch Hartwell, P.C.

Street Address: 520 S.W. Yamhill Street, Suite 200

City: Portland

State: Oregon Zip: 97204

Phone Number: (503) 224-6655

Fax Number: (503) 295-6679

Email Address: anton@khpatent.com

6. Total number of applications and patents involved: one**7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00**

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Informationa. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature:*Anton E. Skaugset*

Signature

September 11, 2006

Date

09/15/2006 DBYRNE 00000035 11471750

Anton E. Skaugset

01 FC:8021

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

ASSIGNMENT

WHEREAS, WE , (1) **Yoshiro AOKI**; (2) **Riyuusuke KASAMATSU**; (3) **Hideki NISHIHATA**; and (4) **Seiichi NAKAMURA**

Of (1) (2) (3) and (4) c/o **SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku,**

Tokyo, Japan respectively, have invented certain improvements in

METHOD FOR MANUFACTURING SIMOX WAFER AND SIMOX WAFER

, for which we have executed an application for Letters Patent of the United States on the date we executed this Assignment as hereinafter set forth.

WHEREAS, **SUMCO CORPORATION**, a Japanese corporation, having its principal place of business in **Tokyo**, Japan, is desirous of acquiring an interest therein:

NOW, THEREFORE, for other good and valuable consideration, we the said (1) **Yoshiro AOKI**; (2) **Riyuusuke KASAMATSU**; (3) **Hideki NISHIHATA** and (4) **Seiichi NAKAMURA**, have sold, assigned, and transferred, and by these presents do sell, assign, and transfer unto the said **SUMCO CORPORATION**, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office officials in the United States and any and all foreign countries to issue any and all of said Letters Patent, when

granted, to the said **SUMCO CORPORATION**, as the assignee of our entire right, title and interest in and to the same, for the sole use of the said **SUMCO CORPORATION**, its successors and assigns.

Further, we agree that we will communicate to the said **SUMCO CORPORATION**, or its representatives any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to the said **SUMCO CORPORATION**, make all rightful oaths and generally do everything possible to aid the said **SUMCO CORPORATION**, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 23th day of June, 2006

Yoshiro Aoki
FIRST INVENTOR **Yoshiro AOKI**

Witness:

(Name)

(Address)

(City, Country)

Ryuusuke Kasamatsu
SECOND INVENTOR **Riyuusuke KASAMATSU**

Witness:

(Name)

(Address)

(City, Country)

Hideki Nishihata
THIRD INVENTOR **Hideki NISHIHATA**

Witness:

(Name)

(Address)

(City, Country)

S. Nakamura
FOURTH INVENTOR **Seiichi NAKAMURA**

Witness:

(Name)

(Address)

(City, Country)